

**SURFACE MOUNT MOLDED TYPE  
POWER INDUCTOR SERIES MTPI0312**

**FEATURES**

- Low profile
- High current handling capacity
- Low noise and low DCR
- High reliability and efficiency
- RoHS compliant and Halogen free

**ELECTRICAL SPECIFICATIONS**

- Inductance range      0.47uH to 10.0uH
- Test frequency        100 KHz with test level 1.0 V
- Test equipment        Quadtech 1910 L analyzer
- Rated current range    1.4 to 7.2 Amps
- Tolerance                ± 20% (M)
- Rated current            Refer to notes below

**PHYSICAL SPECIFICATIONS**

- Operating temp.        -40°C to +125°C
- Core                      Mixed material
- Terminal construction Solder plating
- Packaging                Box    8000 pieces per inner box  
                                  T & R 4000 pieces per reel
- Tape & reel spec.      Tape 12 mm embossed carrier  
                                  Reel 330 mm reel

**SPECIFICATIONS**

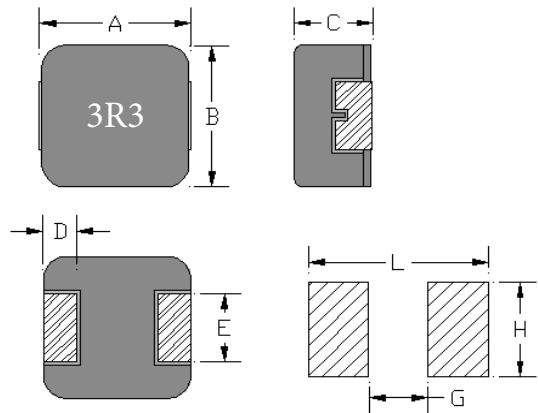
Part Number	L (μH)	Tol % ±	DCR max (mΩ)	Rated Current (A)	
				I <sub>rms</sub> <sup>(1)</sup>	I <sub>sat</sub> <sup>(2)</sup>
MTPI0312-R47M	0.47	20	30.0	5.0	7.2
MTPI0312-R56M	0.56	20	36.0	4.5	6.6
MTPI0312-R68M	0.68	20	40.0	4.0	6.1
MTPI0312-R82M	0.82	20	48.0	3.5	5.8
MTPI0312-1R0M	1.00	20	60.0	3.3	5.5
MTPI0312-1R5M	1.50	20	85.0	3.0	4.0
MTPI0312-2R2M	2.20	20	115.0	2.7	3.4
MTPI0312-3R3M	3.30	20	210.0	2.0	3.1
MTPI0312-4R7M	4.70	20	293.0	1.6	2.8
MTPI0312-5R6M	5.60	20	360.0	1.5	2.2
MTPI0312-6R8M	6.80	20	400.0	1.4	2.0
MTPI0312-8R2M	8.20	20	463.0	1.2	1.7
MTPI0312-100M	10.0	20	550.0	1.0	1.4

**DIMENSIONS IN MILLIMETERS**

- Length A                    3.5 ± 0.2
- Width B                    3.2 ± 0.2
- Height C                    1.0 ± 0.2
- Terminal width D         0.7 ± 0.2
- Terminal length E        1.2 ± 0.2

**SUGGESTED LAND PATTERN**

- L = 4.1 mm ref.
- G = 1.9 mm ref.
- H = 1.45 mm ref.



Notes:

- (1) Based on ΔT approximately 40°C rise
- (2) L drops 30% typical

All test data based on 25°C ambient  
 Part temperature (ambient + temperature rise) must not exceed 125°C under worst case operating conditions.  
 Circuit design, components, PCB trace size, airflow and other cooling provisions all effect the part temperature.